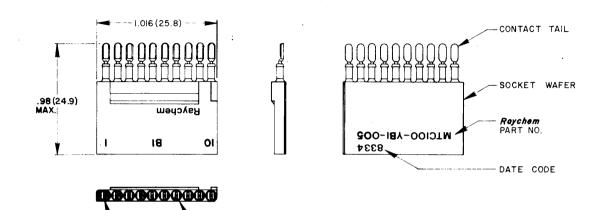
હ્યા 1હ			
LTH	g og have a fill fig.	DATE	APPROVED
N/C	INITIAL RELEASE, ECN NO. T-4125	8-9-82	93



NOTES:

I. MATERIAL; I-A SOCKET WAFER; INSERT MATERIAL HIGH GRADE POLYARYLENE THERMOPLASTIC

I-B SOCKET CONTACT; COPPER ALLOY PER QQ-B-750

2. FINISH; 2-A SOCKET WAFER; FINISH TO BE MOLDED

2-B SOCKET CONTACT ENGAGING AREA; GOLD PLATE PER MIL-G-45204, CLASS I

SOCKET CONTACT

IO EACH EQUALLY SPACED

2-C CONTACT TAIL: SOLDER COATED PER QQ-S-571 Sn63

3. WAFER; WAFER DESIGNED FOR USE WITH CONNECTORS DESIGNED TO Raychem SPECIFICATION D-6012

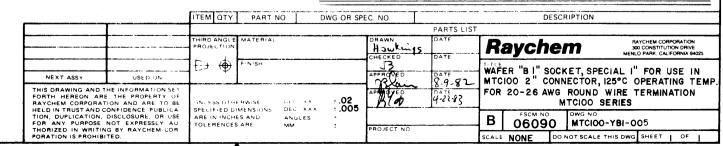
4. SOCKET ONE; SOCKET NUMBER ONE MARKED IN CONTRASTING COLOR.

©Raychem Corporation 1982

5. WEIGHT (MAX); <u>LBS. GRAMS</u> .0044 2.02

SOCKET ONE

## SPECIFICATION CONTROL DRAWING



If this document is printed it becomes uncontrolled. Check with the web for latest revision.